



TC-SPA-3.0 Series

Shin-Etsu Silicones of America, Inc.
800-544-1745

Product Features

- Ultra soft and compressible
- Non-electrically insulating
- Excellent thermal conductivity
- 0.50, 1.00, 1.50, 2.00, 2.50, and 3.00mm thicknesses available
- Low stress and contact thermal resistance
- UL 94 V-0 rated

Typical Applications

- Vehicle modules
- Power supplies
- LED modules

Typical Properties

Type	Soft and Ultra Soft Thermal Pads
UL	Y
Low Molecular Weight Siloxane Stripped?	Y
Color	Gray
Density @ 23C (g/cm ³)	2.40
Shore 00 Hardness	21
Thermal Conductivity (W/m·K)	3.00
Thermal Resistance (C/W)	0.42
Usable Temp. Range (C)	-40 to +180
Thickness (mm)	1.0
Sheet Size (mm)	300 x 400

Note: Values are not for specification purposes.

Physical properties are typical for the thickness given. Other thicknesses may have slightly varying properties and are available upon request.

Warranty- The information and data contained herein are believed to be accurate and reliable; however it is the user's responsibility to determine suitability of use. Since Shin-Etsu Silicones, Inc. cannot know all of the uses to which its products may be put or the conditions of use, it makes no warranties concerning the fitness or suitability of its products for a particular use or purpose. You should thoroughly test any proposed use of our products and independently conclude satisfactory performance in your application. Likewise, if the manner in which our products are used requires governmental approval or clearance, you must obtain it. Shin-Etsu Silicones, Inc. warrants only that its products will meet its specifications. There is no warranty of merchantability of fitness of use, nor any other expressed or implied warranties. The user's exclusive remedy and Shin-Etsu Silicones, Inc.'s sole liability is limited to refund of the price or replacement of any product shown to be otherwise than as warranted. Shin-Etsu Silicones, Inc. will not be liable for incidental or consequential damages of any kind. Suggestions of uses should not be taken as inducements to infringe any patents.